



Customer Information Notification

202411011I : Datasheet Update for TJA1044(V) and TJA1057 Products

Note: This notice is NXP Company
Proprietary.

Issue Date: Nov 22, 2024 **Effective Date:** Dec 23, 2024

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Management summary

Datasheet update for TJA1044(V) and TJA1057 products

Change Category

- | | | | | |
|--|---|--|--|---|
| ☐ Wafer
Fab Process | ☐ Assembly
Process | ☐ Product Marking | ☐ Test
Process | ☐ Design |
| ☐ Wafer
Fab
Materials | ☐ Assembly
Materials | ☐ Mechanical
Specification | ☐ Test
Equipment | ☐ Errata |
| ☐ Wafer
Fab
Location | ☐ Assembly
Location | ☐ Packing/Shipping/Labeling | ☐ Test
Location | ☐ Electrical
spec./Test
coverage |
| ☐ Firmware | ☒ Other: Datasheet update | | | |

Notification Overview

Description

NXP Product Line In-Vehicle Networking (PL IVN) is updating the datasheets of products TJA1044(V) and TJA1057. The two primary improvements are:

- Compliance to the new ISO 11898-2:2024 standard, and associated reformatting of timing characteristics
- Addition of SAE J2962-2:2019 ESD specifications for specific product versions

Note that no change whatsoever has been made to the products, this is purely a datasheet update. The datasheets revision history specifies all the updates.

Attached to this Customer Information Notification (CIN) are six additional documents:

- A pdf document with detailed information on the datasheet updates
- The ZVEI Delta Qualification Matrix (DeQuMa) for these datasheet updates, both in zipped excel and pdf format. The applicable change ID numbers are SEM-DS-02 and SEM-DS-03
- The new TJA1044 datasheet
- The new TJA1044V datasheet
- The new TJA1057 datasheet

The new datasheets will also be published on the NXP website (www.NXP.com) one month after the distribution of this CIN to customers.

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents.

Reason

NXP PL IVN wants to properly inform you of the improved datasheet specifications for the TJA1044(V) and TJA1057 products.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new data sheet will be issued

Additional information

Additional documents: [view online](#)

Remarks

As direct recipient of this NXP PL IVN PCN, please use the 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files'. If you're not the original recipient, i.e. this CIN has been forwarded to you, you should contact the original recipient(s) within your company to obtain the attachments.

Should you, after having read both CIN and its attachment with detailed explanation, still have questions, please contact us via below e-mail address.

Related Notification

Notification	Issue Date	Effective Date	Title
202302008I	Feb 17, 2023	Mar 17, 2023	TJA1044 Datasheet Update
202302010I	Feb 17, 2023	Mar 17, 2023	TJA1057 Datasheet Update
202309003F04	Feb 21, 2024	May 21, 2024	Introduction of Multi-Source Optical Shrink Versions of SO-Package Product TJA1044
202309003F05	Feb 21, 2024	May 21, 2024	Introduction of Multi-Source Optical Shrink Versions of SO-Package Product TJA1057

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position	Quality Account Manager
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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